

[54] DEFECT INSPECTION DEVICE FOR SEMICONDUCTORS

4,755,746 7/1988 Mallory et al. 324/73 AT

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[**] Term: 14 Years

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[30] Foreign Application Priority Data

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[52] U.S. Cl. D10/46

[58] Field of Search D10/46, 75, 76, 102; 73/849; 250/472.1, 473; 324/73 R, 73 AT, 73 PC, 158; D16/27

[56] References Cited

U.S. PATENT DOCUMENTS

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Toshiba, "A Defect Inspection Device for Semiconductors", Dec. 5, 1961.

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[57] CLAIM

The ornamental design for a defect inspection device for semiconductors, as shown.

DESCRIPTION

FIG. 1 is a front, top and left side perspective view of a defect inspection device for semiconductors showing my new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a left side elevational view thereof;

FIG. 6 is a rear elevational view thereof; and

FIG. 7 is a bottom plan view thereof.

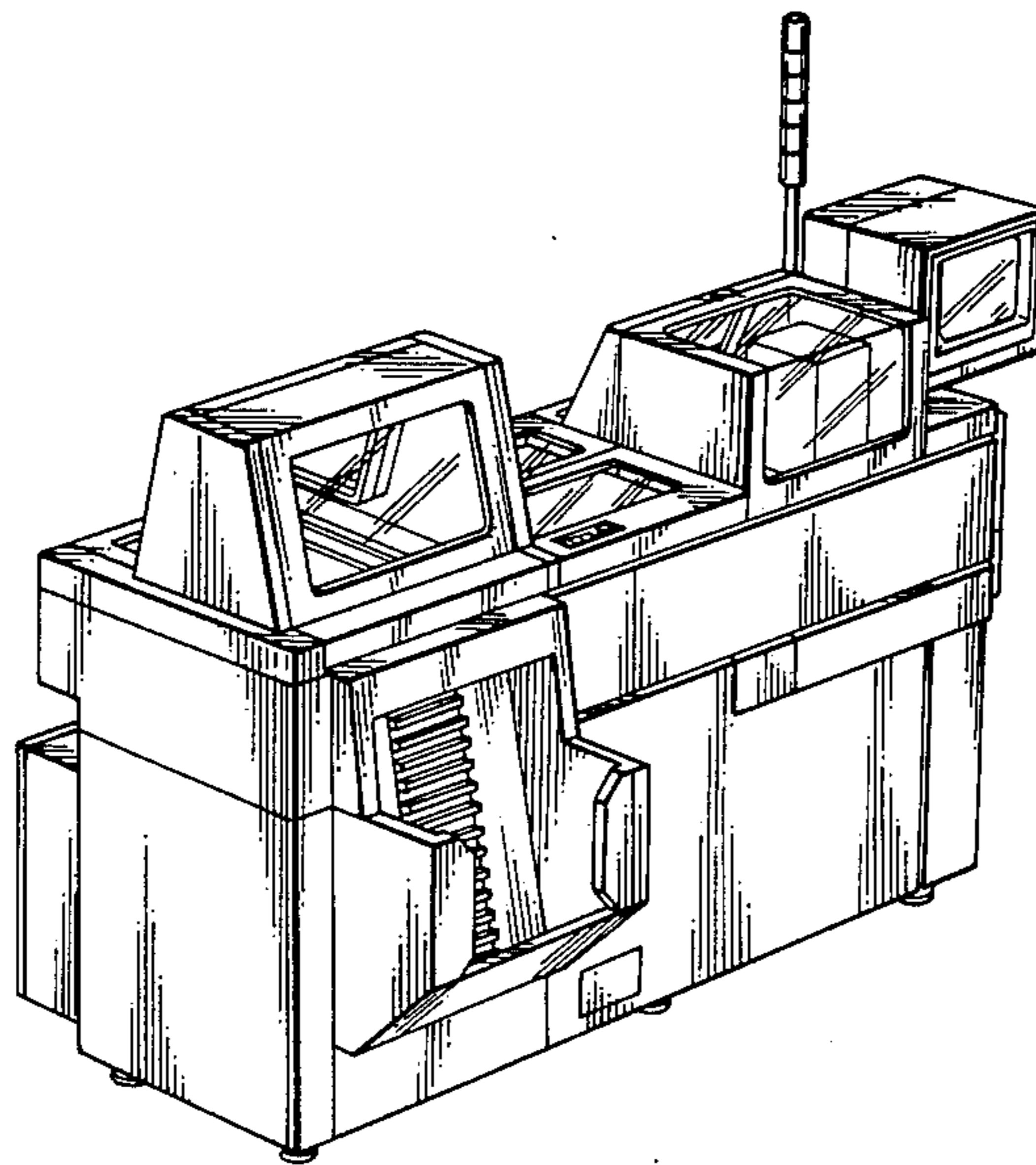


FIG. 1

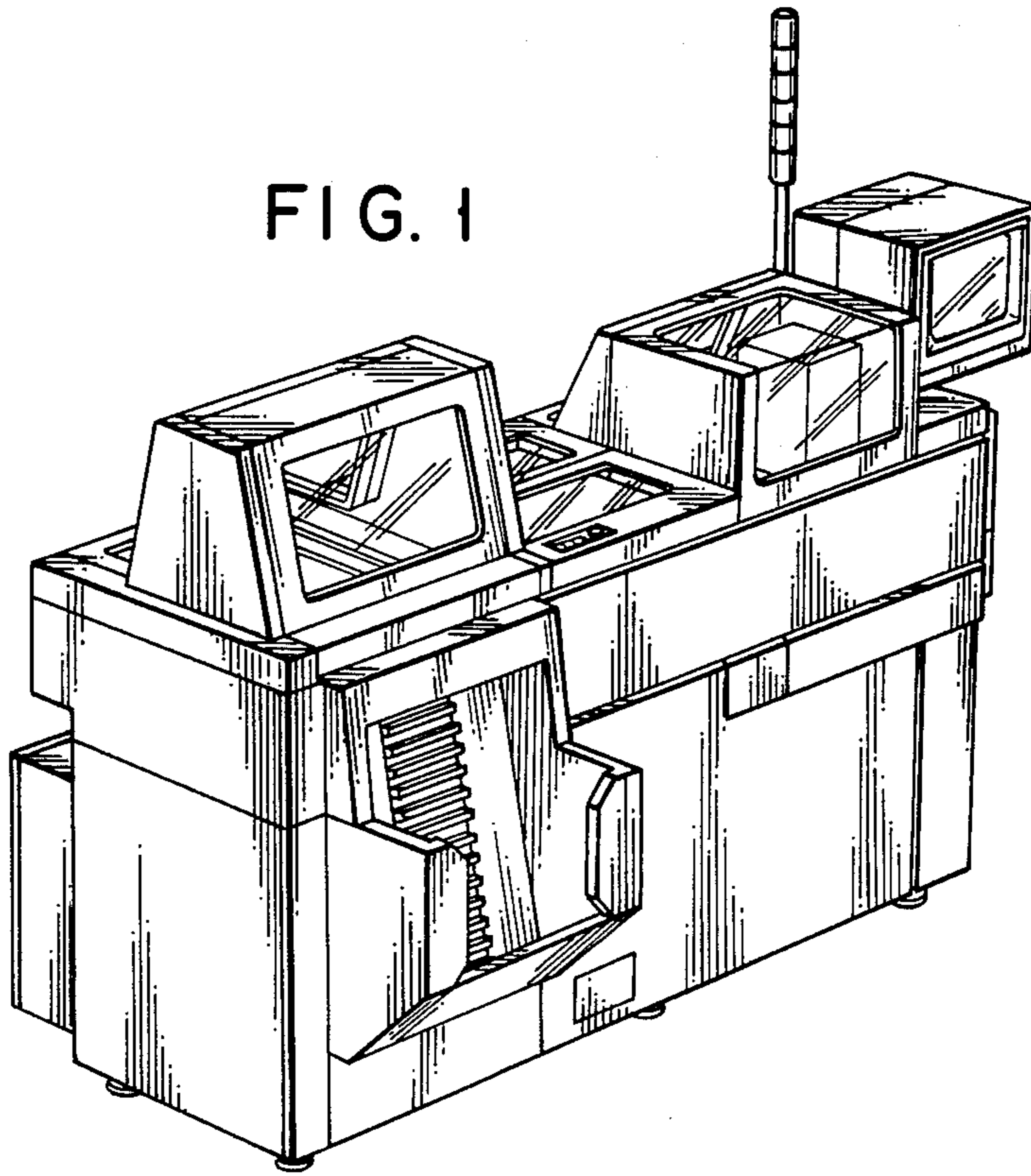


FIG. 2

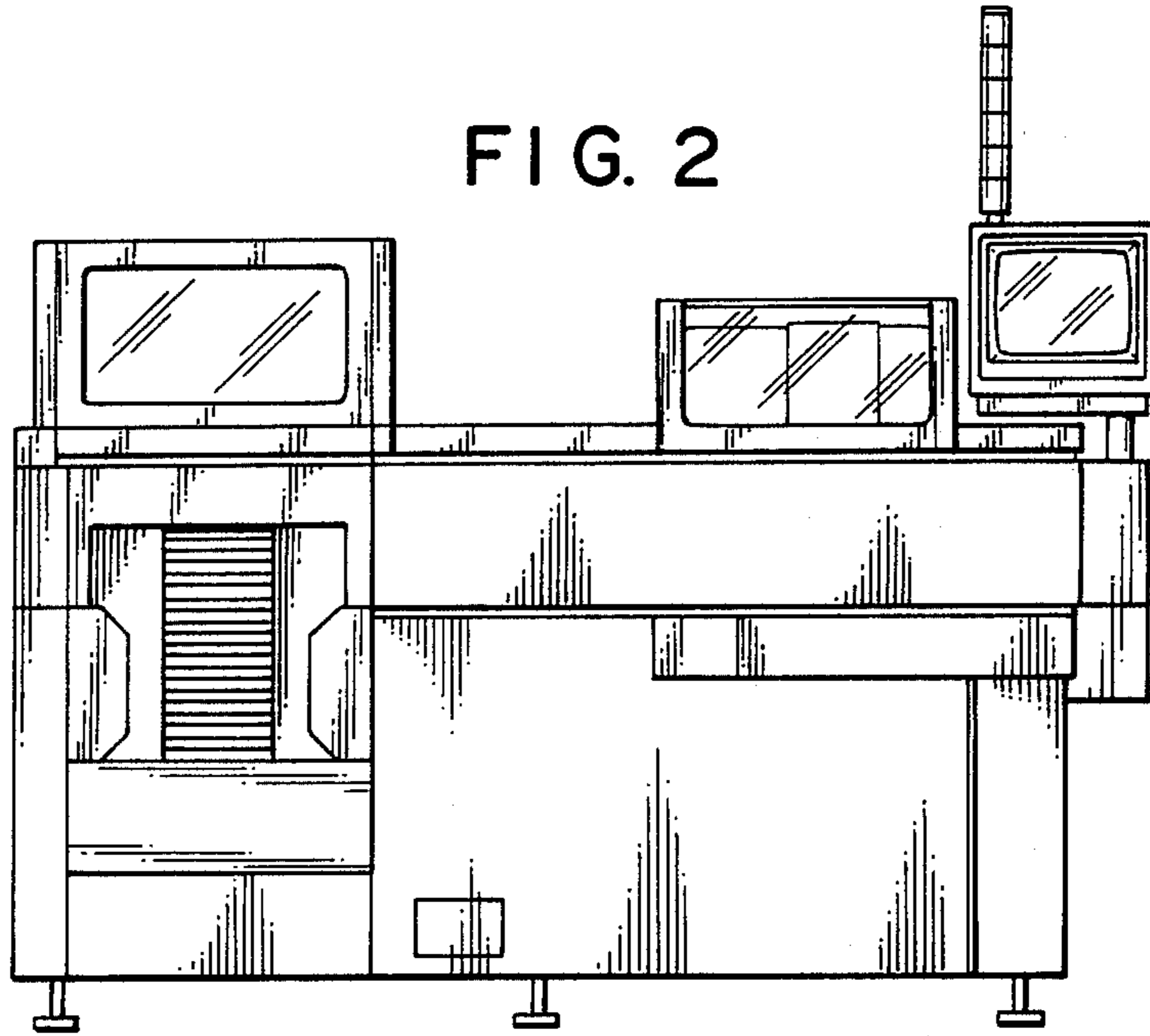


FIG. 3

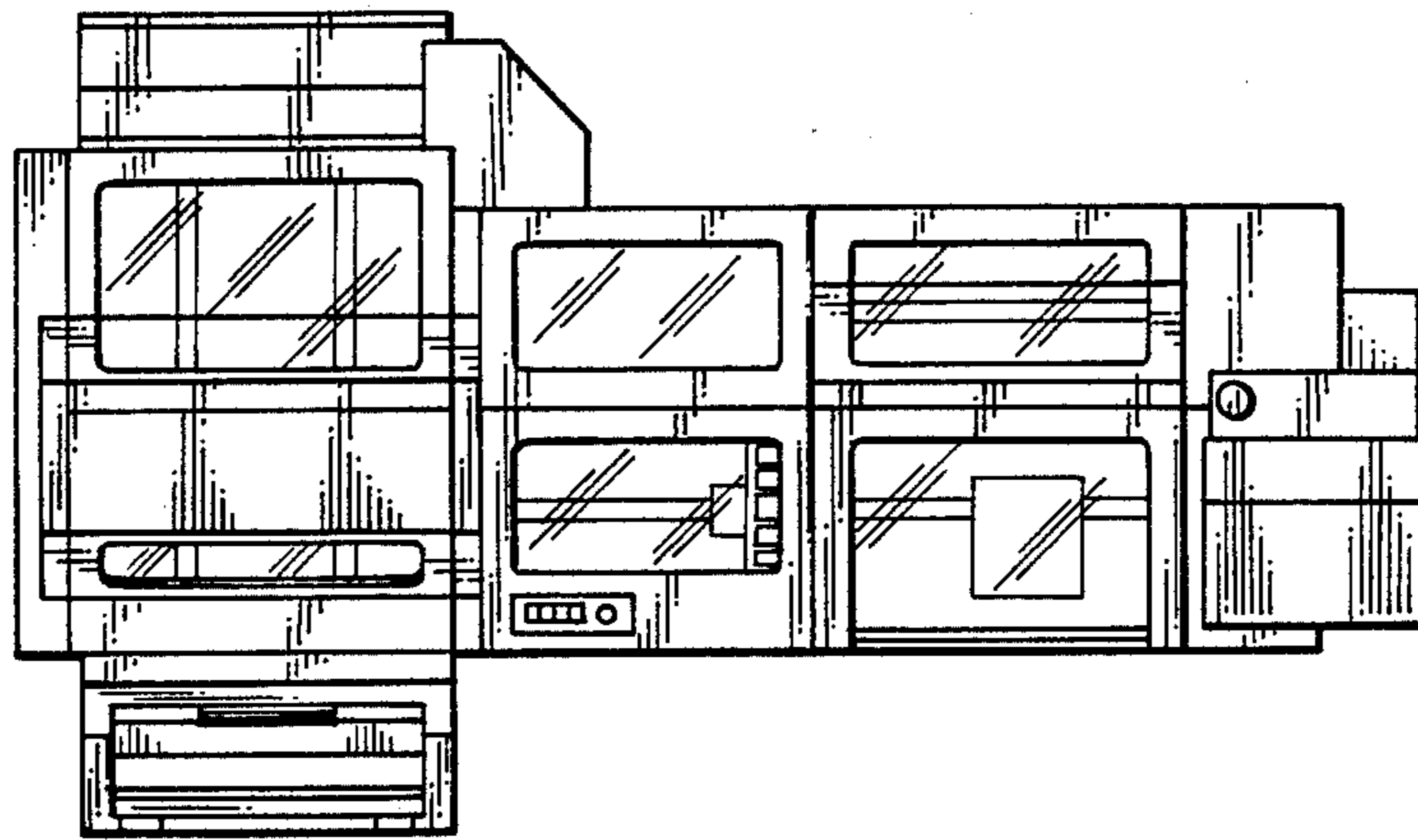


FIG. 4

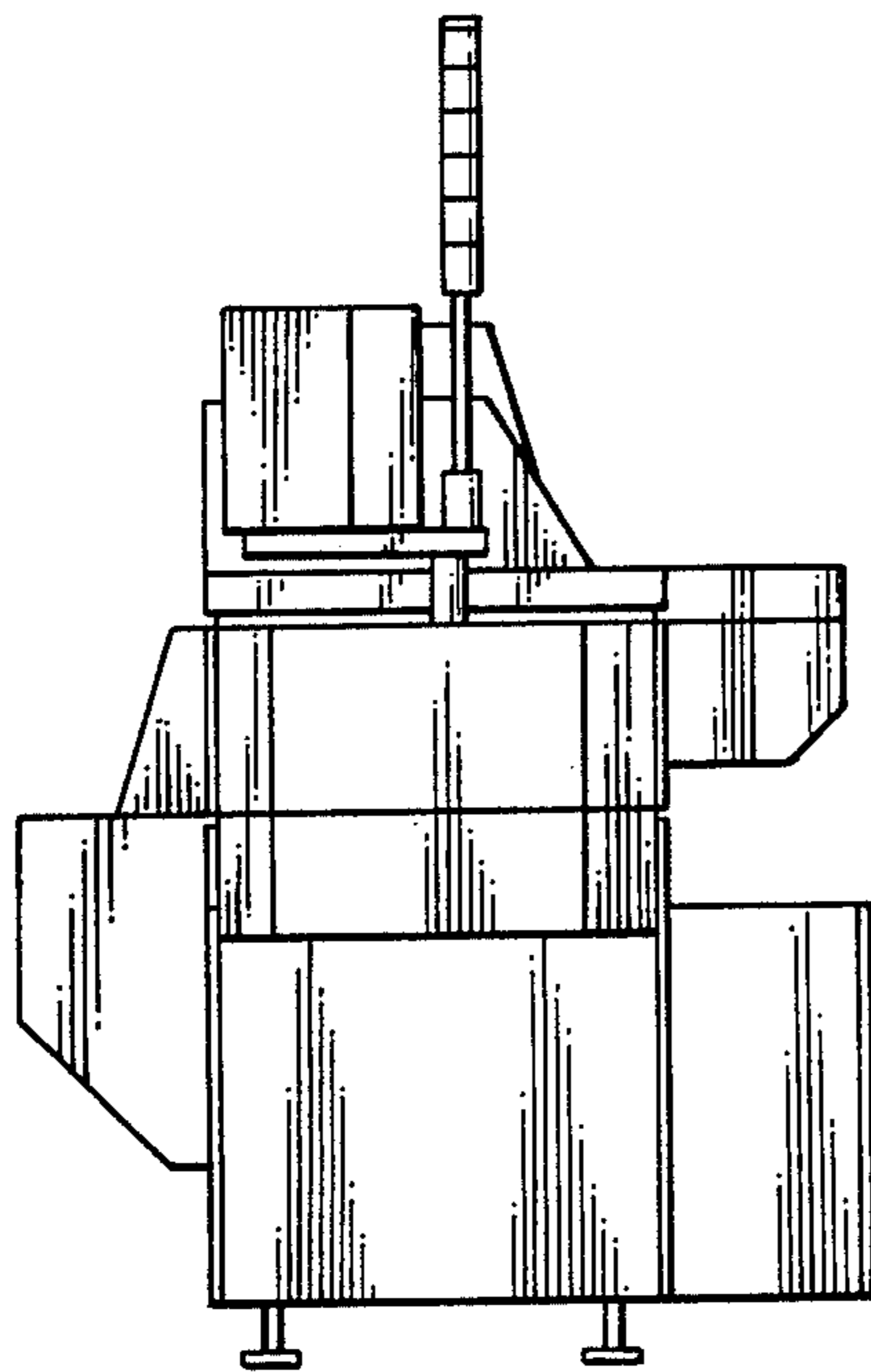


FIG. 5

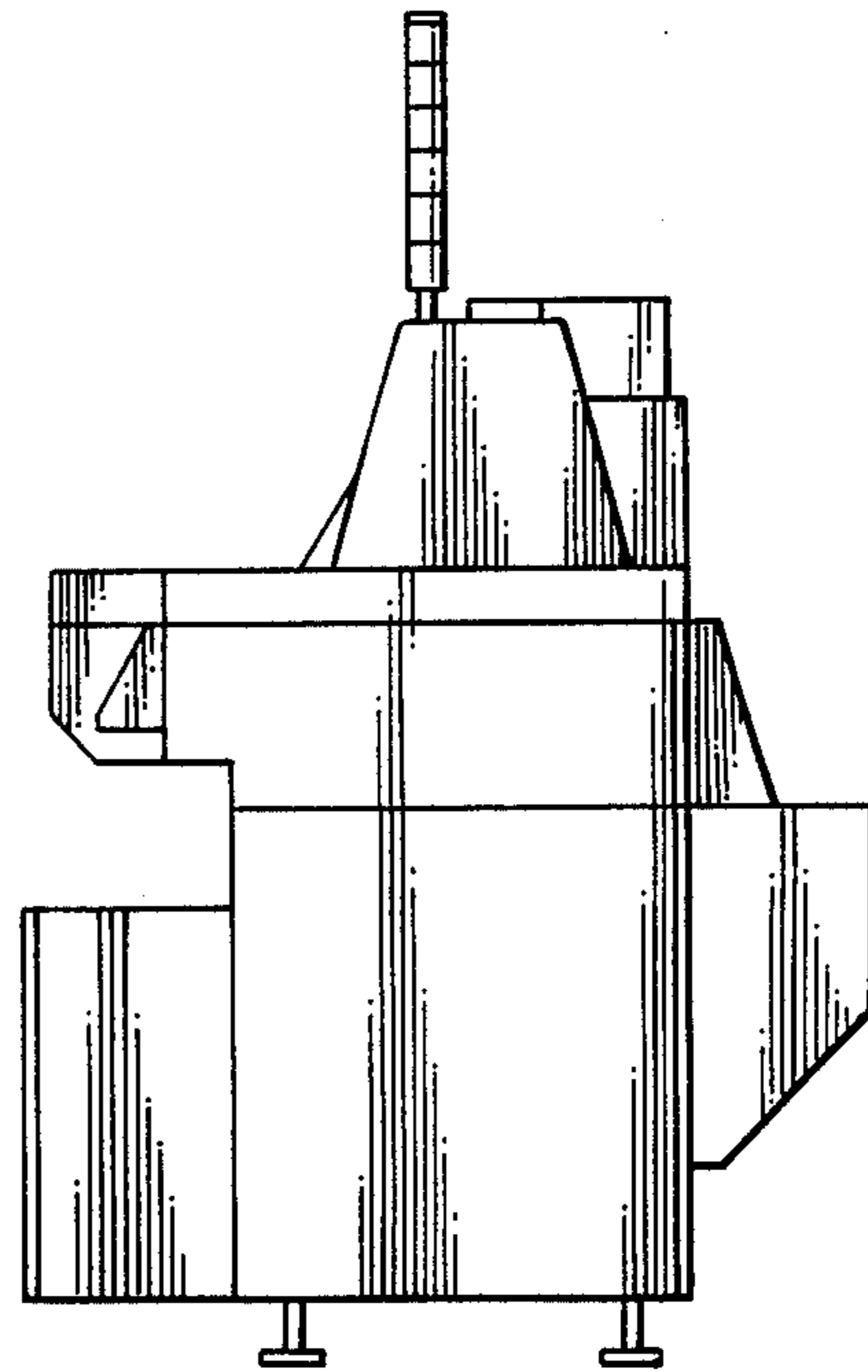


FIG. 6

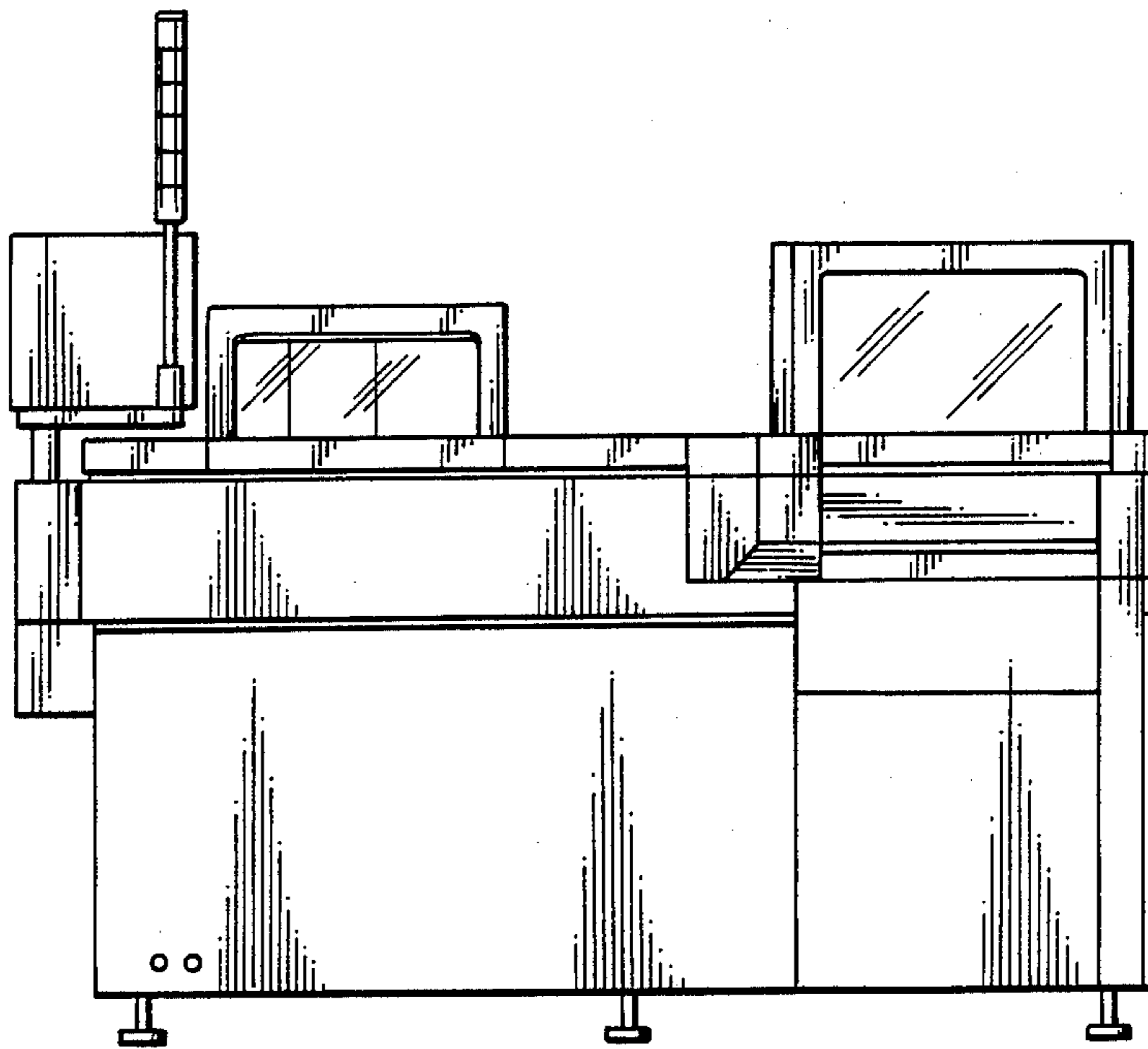


FIG. 7

